

Product Features

- Exceptional thermal conductivity
- Excellent electrical properties
- UL-94 V-0 equivalent flame rating
- Superior reworkability

Typical Applications

- Electronics applications requiring thermal dissipation

Typical Properties

Type	Liquid-dispensed Gap Filling Rubber
Cure Type	Addition
One/Two Component	Two
Low Molecular Weight Siloxane Stripped?	Y
Color	Pink
Density @ 23C (g/cm ³)	3.20
Viscosity (Pa·s)	284
Mix Ratio by Weight	100:100
Cure Conditions	24hr @ 25C
Tack Free Time (min)	360
Working Time	4 Hours
Shore 00 Hardness	61
Tensile Strength (MPa)	0.10
% Elongation	20
Volume Resistivity (TΩ·m)	2.800
Dielectric Strength (kV/mm)	20.0
Dielectric Dissipation Factor	4 x 10 ⁻³ @ 50Hz
Dielectric Constant	5.3 @ 50Hz
Thermal Conductivity (W/m·K)	6.50
Usable Temp. Range (C)	-40 to +180

Note: Values are not for specification purposes.

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